Bipolar Power Transistors 40 V, 3.0 A, Low V_{CE(sat)} **PNP Transistor**

ON Semiconductor's e²PowerEdge family of low V_{CE(sat)} transistors are surface mount devices featuring ultra low saturation voltage (V_{CE(sat)}) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers. WWW.DZSG.GON

• These are Pb-Free Devices



ON Semiconductor®

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PNP TRANSISTOR 3.0 AMPERES 40 VOLTS, 2.0 WATTS



MARKING DIAGRAM



SOT-223 CASE 318E STYLE 1



= Assembly Location

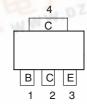
Year

= Work Week

= Specific Device Code 40300

= Pb-Free Package

PIN ASSIGNMENT



Top View Pinout

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.



MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	40	Vdc
Collector-Base Voltage	V _{CB}	40	Vdc
Emitter-Base Voltage	V _{EB}	6.0	Vdc
Base Current - Continuous	I _B	1.0	Adc
Collector Current - Continuous - Peak	I _C	3.0 5.0	Adc
Total Power Dissipation Total P _D @ T _A = 25°C mounted on 1" sq. (645 sq. mm) Collector pad on FR-4 bd material Total P _D @ T _A = 25°C mounted on 0.012" sq. (7.6 sq. mm) Collector pad on FR-4 bd material	P _D	2.0 0.80	W
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case - Junction-to-Ambient on 1" sq. (645 sq. mm) Collector pad on FR-4 bd material - Junction- to- Ambient on 0.012" sq. (7.6 sq. mm) Collector pad on FR-4 bd material		64 155	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	TL	260	°C

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS40300MZ4T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel
NSS40300MZ4T3G	SOT-223 (Pb-Free)	4000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Collector-Emitter Sustaining Voltage (I _C = 10 mAdc, I _B = 0 Adc)	V _{CEO(sus)}	40	-	-	Vdc	
Emitter-Base Voltage ($I_E = 50 \mu Adc$, $I_C = 0 Adc$)	V _{EBO}	6.0	-	-	Vdc	
Collector Cutoff Current (V _{CB} = 40 Vdc)	Ісво	-	-	100	nAdc	
Emitter Cutoff Current (V _{BE} = 6.0 Vdc)	I _{EBO}	-	-	100	nAdc	
ON CHARACTERISTICS (Note 1)						
Collector-Emitter Saturation Voltage ($I_C = 0.5 \text{ Adc}$, $I_B = 50 \text{ mAdc}$) ($I_C = 1.0 \text{ Adc}$, $I_B = 20 \text{ mAdc}$) ($I_C = 3.0 \text{ Adc}$, $I_B = 0.3 \text{ Adc}$)	V _{CE(sat)}			0.070 0.150 0.400	Vdc	
Base-Emitter Saturation Voltage (I _C = 1.0 Adc, I _B = 0.1 Adc)	V _{BE(sat)}	-	-	1.0	Vdc	
Base-Emitter On Voltage (I _C = 1.0 Adc, V _{CE} = 2.0 Vdc)	V _{BE(on)}	-	-	0.9	Vdc	
DC Current Gain $ \begin{array}{l} (I_{C}=0.5 \; \text{Adc}, V_{CE}=1.0 \; \text{Vdc}) \\ (I_{C}=1.0 \; \text{Adc}, V_{CE}=1.0 \; \text{Vdc}) \\ (I_{C}=3.0 \; \text{Adc}, V_{CE}=1.0 \; \text{Vdc}) \end{array} $	h _{FE}	200 175 100	- - -	- 350 -	-	
DYNAMIC CHARACTERISTICS						
Output Capacitance (V _{CB} = 10 Vdc, f = 1.0 MHz)	C _{ob}	-	40	-	pF	
Input Capacitance (V _{EB} = 5.0 Vdc, f = 1.0 MHz)	C _{ib}	-	130	-	pF	
Current-Gain - Bandwidth Product (Note 2) (I _C = 500 mA, V _{CE} = 10 V, F _{test} = 1.0 MHz)	f _T	-	160	-	MHz	

^{1.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%. 2. $f_T = |h_{FE}| \bullet f_{test}$

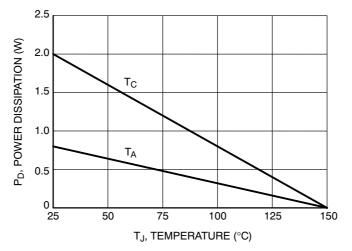
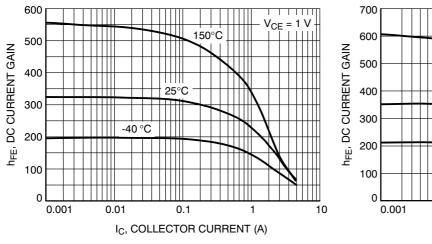


Figure 1. Power Derating

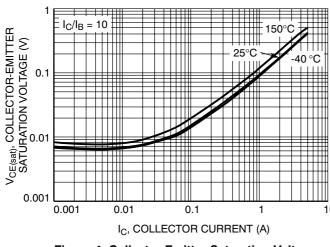
TYPICAL CHARACTERISTICS



 $V_{CE} = 4 V$ 150°C -40 °C 0.01 0.1 10 I_C, COLLECTOR CURRENT (A)

Figure 2. DC Current Gain

Figure 3. DC Current Gain



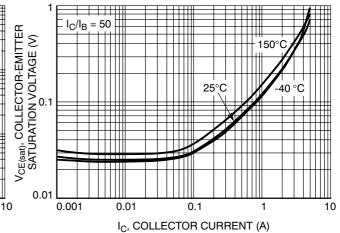
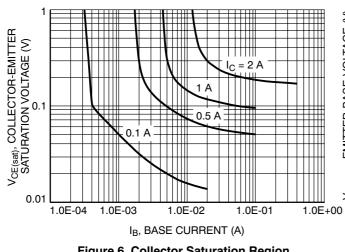


Figure 4. Collector-Emitter Saturation Voltage

Figure 5. Collector-Emitter Saturation Voltage



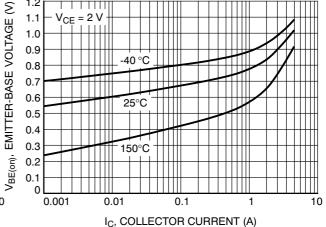


Figure 6. Collector Saturation Region

Figure 7. $V_{BE(on)}$ Voltage

1.2

1.1

TYPICAL CHARACTERISTICS

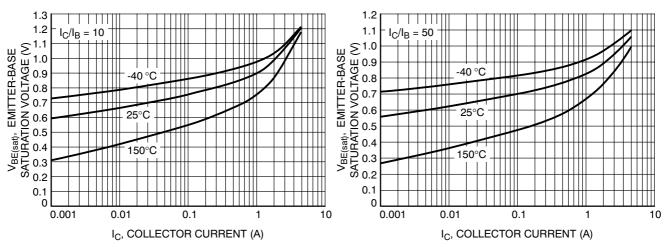


Figure 8. Base-Emitter Saturation Voltage



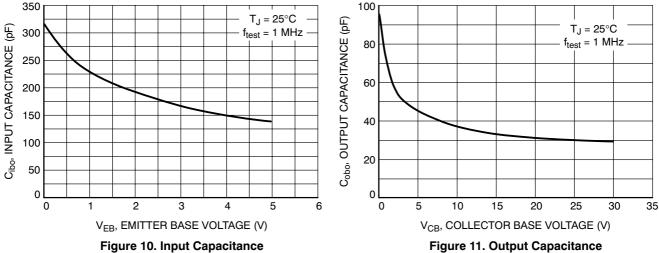


Figure 10. Input Capacitance

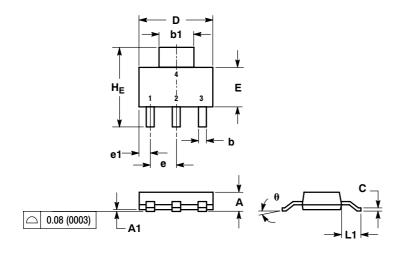
200 10 $T_J = 25^{\circ}C$ 180 Ic, COLLECTOR CURRENT (A) f_{test} = 1 MHz f_{Tau}, CURRENT BANDWIDTH 0.5 ms 160 = 10 V PRODUCT (MHz) 120 80 60 10 ms 100 ms 0.1 40 20 0.01 0.001 0.01 0.1 10 100 V_{CE} , COLLECTOR-EMITTER VOLTAGE (V) I_C, COLLECTOR CURRENT (A)

Figure 12. Current-Gain Bandwidth Product

Figure 13. Safe Operating Area

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 ISSUE L

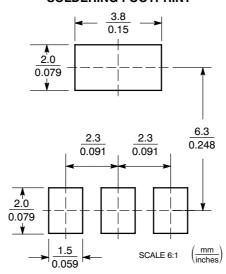


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 VALEEM 1000
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
O	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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